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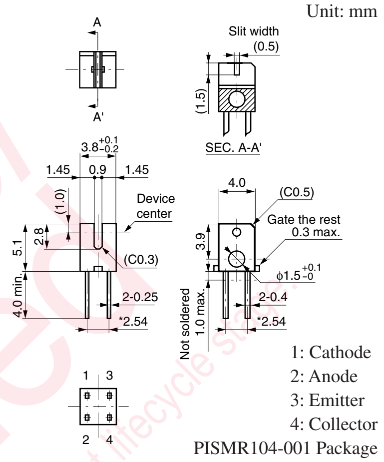
CNZ1002 (ON1002)

Photo Interrupter

For contactless SW, object detection



1: Cathode
2: Anode
3: Emitter
4: Collector
PISMR104-001 Package

(Note) 1. Tolerance unless otherwise specified is ±0.2
2. ( ) Dimension is reference
3. ∗ is dimension at the root of leads
4. Burrs should be less than 0.15 mm

■ Overview

CNZ1002 is an ultraminiature, highly reliable transmissive photosensor in which a high efficiency GaAs infrared light emitting diode chip and a high sensitivity Si phototransistor chip are integrated in a double molded resin package.

■ Features

- Ultraminiature: 4.0 mm × 3.8 mm (height: 5.1 mm)
- Fast response: t_r , t_f = 35 μs (typ.)
- Highly precise position detection: 0.25 mm
- Gap width: 0.9 mm

■ Absolute Maximum Ratings $T_a = 25°C$

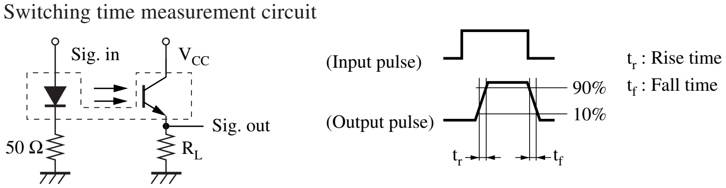
Parameter		Symbol	Rating	Unit
Input (Light emitting diode)	Reverse voltage	V_R	6	V
	Forward current	I_F	50	mA
	Power dissipation *1	P_D	75	mW
Output (Photo transistor)	Collector-emitter voltage (Base open)	V_{CEO}	35	V
	Emitter-collector voltage (Base open)	V_{ECO}	6	V
	Collector current	I_C	20	mA
	Collector power dissipation *2	P_C	75	mW
Temperature	Operating ambient temperature	T_{opr}	−25 to +85	°C
	Storage temperature	T_{stg}	−40 to +100	°C

Note) ∗1: Input power derating ratio is 1.0 mW/°C at $T_a \geq 25°C$.
∗2: Output power derating ratio is 1.0 mW/°C at $T_a \geq 25°C$.

■ Electrical-Optical Characteristics $T_a = 25°C \pm 3°C$

Parameter		Symbol	Conditions	Min	Typ	Max	Unit
Input characteristics	Forward voltage	V_F	I_F = 20 mA		1.2	1.4	V
	Reverse current	I_R	V_R = 3 V			10	μA
Output characteristics	Collector-emitter cutoff current (Base open)	I_{CEO}	V_{CE} = 20 V			100	nA
Transfer characteristics	Collector current	I_C	V_{CE} = 5 V, I_F = 1.5 mA	65		480	μA
	Collector-emitter saturation voltage	$V_{CE(sat)}$	I_F = 3 mA, I_C = 30 μA			0.4	V
	Rise time *	t_r	V_{CC} = 5 V, I_C = 0.1 mA		35		μs
	Fall time *	t_f	R_L = 1 000 Ω		35		μs

Note) 1. Input and output are practiced by electricity.
2. This device is designed be disregarded radiation.
3. ∗: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.

Maintenance/Discontinued
Maintenance/Discontinued includes following four Product lifecycle stage. planed maintenance type, maintenance type, planed discontinued typed, discontinued type
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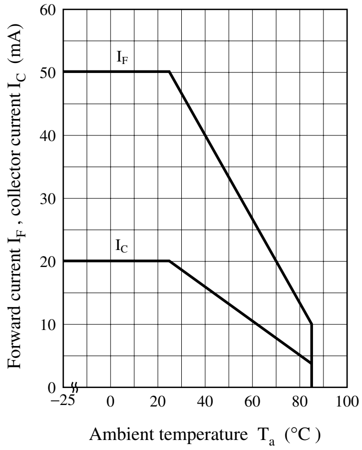
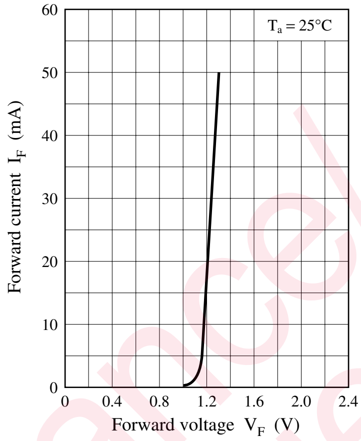
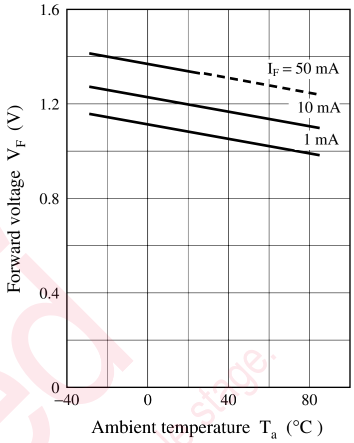
I_F , I_C — T_a



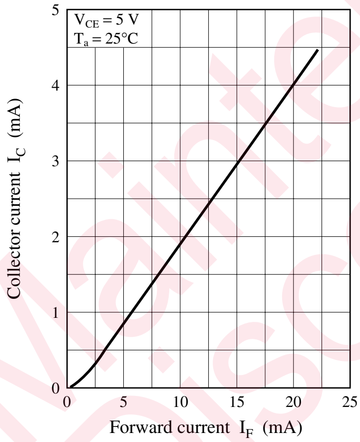
I_F — V_F



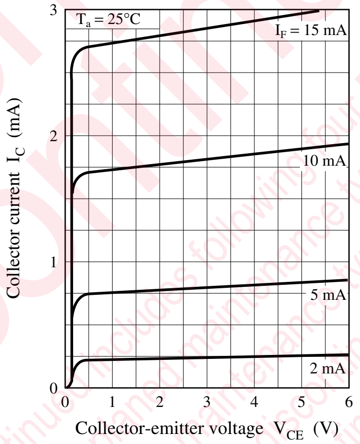
V_F — T_a



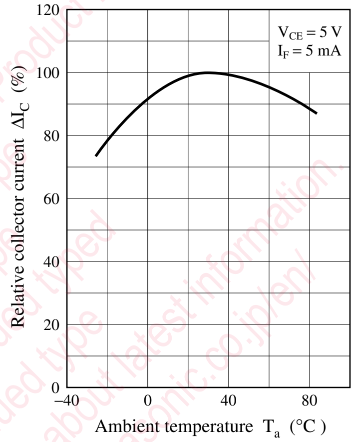
I_C — I_F



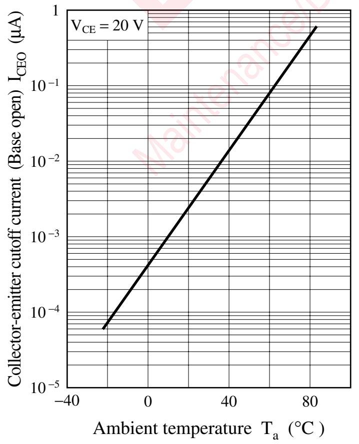
I_C — V_{CE}



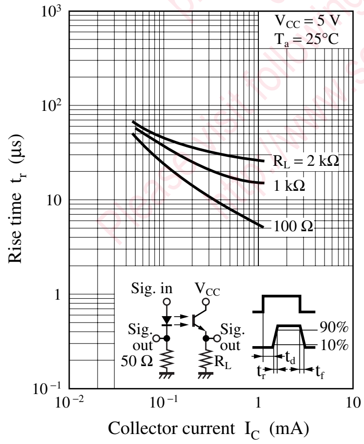
ΔI_C — T_a



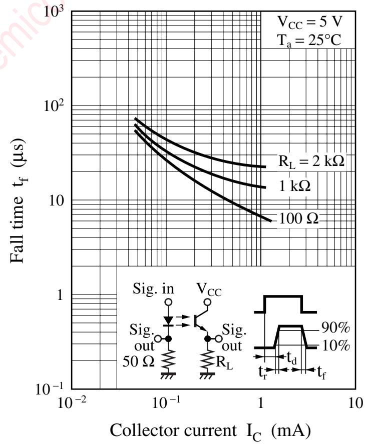
I_{CEO} — T_a



t_r — I_C



t_f — I_C



Maintenance/ Discontinued
Maintenance/Discontinued includes following four Product lifecycle stage.
planed maintenance type, maintenance type, planed discontinued typed, discontinued type
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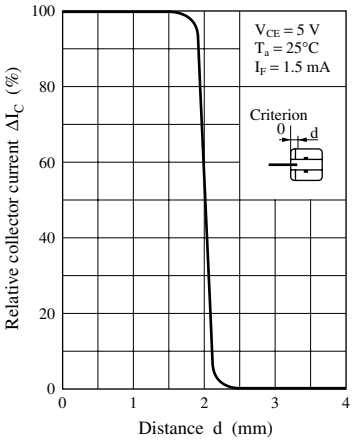
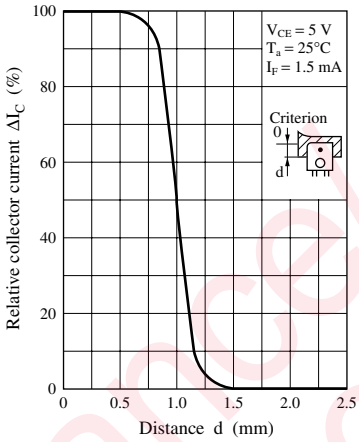
ΔI_C — d (1)



ΔI_C — d (2)



Maintenance/Discontinued
Discontinued includes following four Product lifecycle stage.
planed maintenance type
maintenance type
planed discontinued typed
discontinued type
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⚠DANGER

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GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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